

SPECIFICATION AND PERFORMANCE

Series	229A-R202	File	229A-R202_SPEC	Date	2026/05/20
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of 229A-R202

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIALS		
NO.	PART NAME	DESCRIPTION
1	Housing	PA9T, UL94V-0, Black
2	Contact	Brass H65 T=0.64mm, gold flash plating
3	Shell	Brass C2680 0.3t, 30~80u" nickel plating

RATING	
Rated Current	3.5 AMP
Rated Voltage	60 VAC
Operating Temperature	-40°C to +85°C
Storage Temperature	-40°C to +85°C
Durability	1000 cycles

ELECTRICAL

Item	Requirement	Test Condition
Contact Resistance	20mΩ max. Shielding 100mΩ max.	IEC 60512-2-1 Test 2a IEC 63171 - Figure 5
Dielectric Strength	No Breakdown	1000V DC : contact to contact IEC 60512-4-1 Test 4a
Insulation Resistance	500MΩ min.	Test Voltage 500V DC, 1 min hold IEC 60512-3-1 Test 3a

MECHANICAL

Item	Requirement	Test Condition
Durability	1000 mating cycles	IEC 60512-9-1, Test 9a
Mating/ Un-mating Force	20N (4.5 lbs-force) max	IEC 60512-13-2, Test 13b
Plug to Jack Retention	50N (11.2 lbs force) min	IEC 60512-15-6, Test 15f

ENVIRONMENTAL

Item	Requirement	Test Condition
Cold Resistance	There shall be no defect that would impair normal operation	-40°C, Mated connectors, 25 cycles t=30 min Recovery time 2 h Comply with method IEC 60512-11d
Heat Resistance	There shall be no defect that would impair normal operation	85°C, Mated connectors, 25 cycles t=30 min Recovery time 2 h Comply with method IEC 60512-11d
Humidity	Meet visual requirements, show no physical damage.	40°C, 93%RH, 21 days Comply with method IEC 60512-11c

SOLDER ABILITY		
Item	Requirement	Test Condition
Solder ability	Wet Solder Coverage: 95% Min.	Solder Temperature: $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Immersion Duration: $4\text{sec.} \pm 1\text{sec.}$ Solder: Sn-3Ag-0.5Cu Flux: RMA 25% Comply with method EIA-364-52
Solder-Heat Resistance	No evidence of deformation or fusion of housing and no physical damage after test.	Test Connector on PC Board. Pre-Heat : $150^{\circ}\text{C} \sim 180^{\circ}\text{C}$, $90 \pm 30\text{sec.}$ Heat : 230°C Min., $30\text{sec.} \pm 10\text{sec.}$ Peak Temp. : $255^{\circ}\text{C} \pm 5^{\circ}\text{C}$, $10 \sim 30\text{sec.}$ Refer to Figure I.

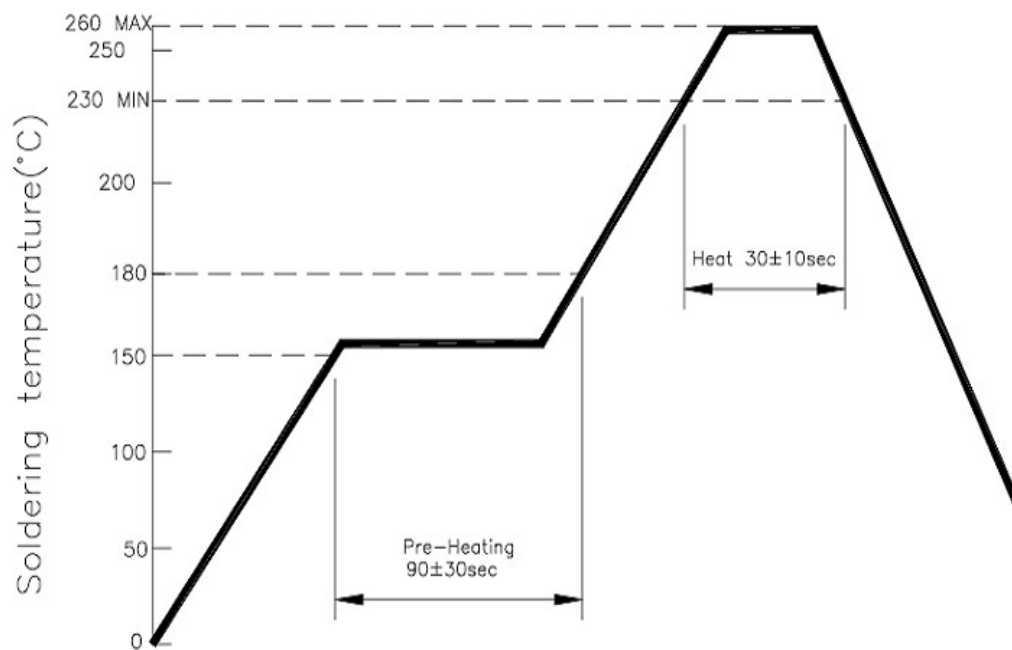


Figure I.